ABSTRACT

A METHOD AND SYSTEM FOR SINGULATION OF INTEGRATED CIRCUITS

A method of singulating a plurality of IC units from a first substrate, comprising the steps of loading the first substrate to a first location on a singulating table, whilst said table is in a first position; performing a first pre-determined cut of a first portion of the first substrate; lifting the first substrate from the singulating table; rotating the singulating table from the first position to a second position; replacing the first substrate to a second location on the singulating table; performing a second pre-determined cut of a second portion of the first substrate so as to singulate the plurality of IC units from the first substrate.

Figure 2



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